

SOT1958-1

FBGA501, plastic fine-pitch ball grid array package, 501 balls,
0.8 mm pitch, 21 mm x 21 mm x 1.63 mm body

26 January 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA501
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-12-2017
Manufacturer package code	98ASA01152D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
package height	-	1.63	1.82	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	501	-	



FBGA501, plastic fine-pitch ball grid array package, 501 balls, 0.8 mm pitch, 21 mm x 21 mm x 1.63 mm body

2 Package outline

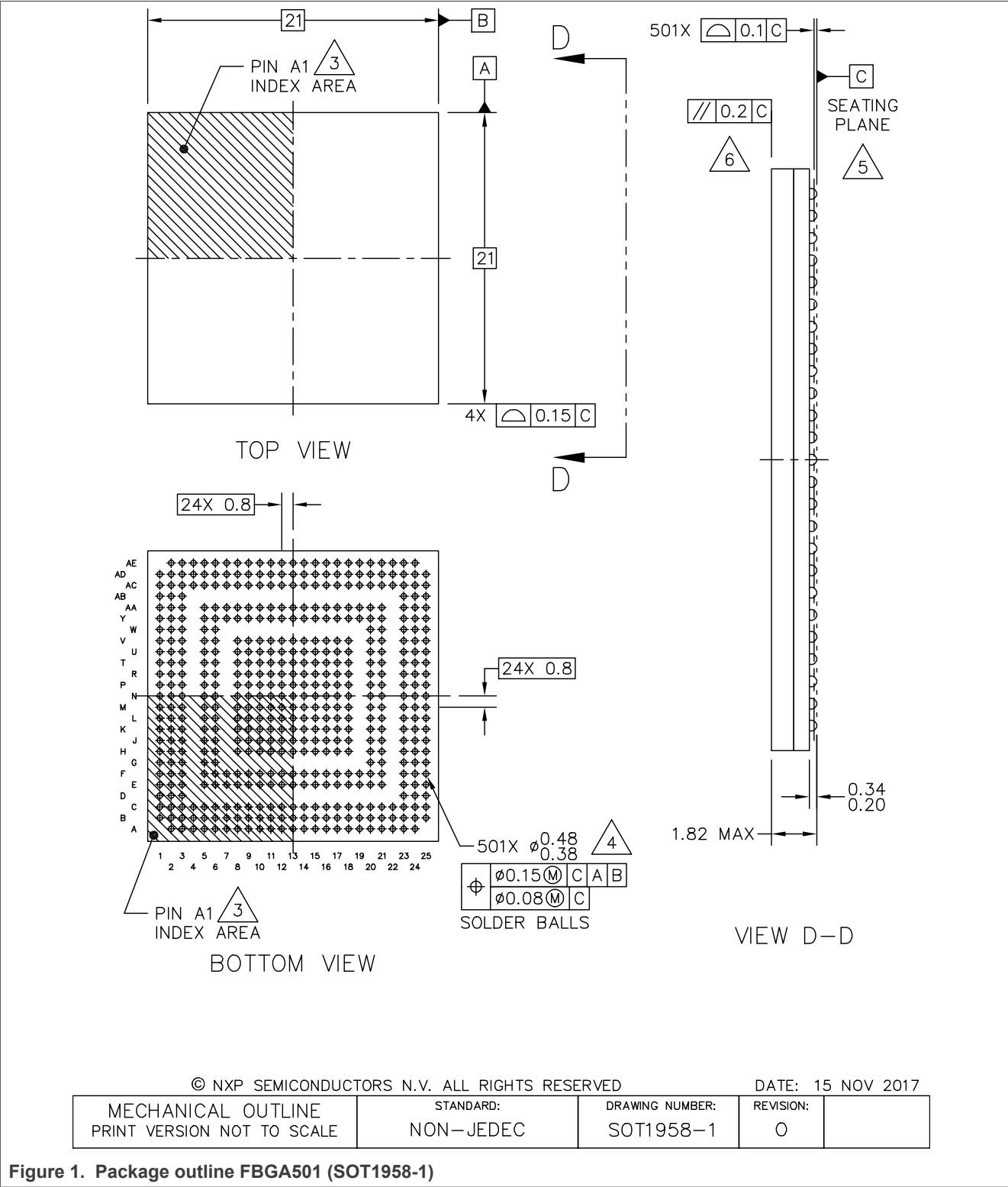


Figure 1. Package outline FBGA501 (SOT1958-1)

FBGA501, plastic fine-pitch ball grid array package, 501 balls, 0.8 mm pitch, 21 mm x 21 mm x 1.63 mm body

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: SOT1958-1	REVISION: 0	

Figure 2. Package outline note FBGA501 (SOT1958-1)

3 Legal information

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